

2022/48819 Attorney Docket:

PATENT

PATENT AND TRADEMARK OFFICE IN THE UNITED STATES

Applicants: Bulent M. Basol et al.

Group Art Unit: 3723 Serial No.: 09/671,800

Examiner: Not Yet Assigned Filed: September 28, 2000

PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL Title:

COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE

AND LAYER STRUCTURE MADE THEREBY

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents 20231 Washington, D.C.

Transmitted herewith is a Preliminary Amendment filing and the filing fee is calculated below:

78	o. After mendment	Highest N Prev. Fil	o. <u>ed</u>	No. Extra	<u>a</u>	Rate	Fee
Total Claims Indep. Claims	38 -	22 3	=	16 2	x x	\$ 9/\$18 = \$40/\$80 =	= \$144 = <u>\$</u>

A check in the amount of \$144.00 is enclosed. XX_{-}

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to XXAccount No. 05-1323 (Docket #2022/48819). A duplicate copy of this sheet is attached.

January 12, 2001

Registration No. 32,390

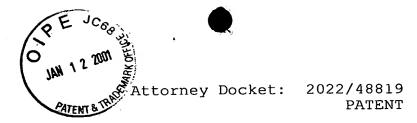
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Title:

PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE

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PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

AI

Please add the following new/claims prior to examination:

A process of making a layer structure usable in manufacturing an integrated circu/t comprising:

producing, in a single apparatus, a structure having deposits of conductive material in features defined in a patterned substrate which are ph/ $\!\!\!/$ sically isolated from each other by providing said patterned substrate, supplying an electrolyte solution out of which said conductive material can be plated, under an applied potential, bver a surface of said patterned substrate, applying a potential so as to deposit a film of said conductive material out of the electrolyte solution and over said surface of said patterned ϕ ubstrate and polishing the film of said conductive material, and removing said conductive material from field regions of said patterned substrate while leaving said deposits of said conductive material in said features defined in said patterned substrate; and

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